Product Change Notification: BLAS-12ZLOM501

Date:

19-Mar-2025

Product Category:

Sequential Linear LED Drivers

Notification Subject:

CCB 6950 Final Notice: Qualification of ASEM as a new assembly site for CL8800K63-G-M935, CL8800K63-G, CL8801K63-G and CL8801K63-G-M935 catalog part numbers (CPN) available in 33L VQFN (6x6x1.0 mm) package.

Affected CPNs:

BLAS-12ZLOM501_Affected_CPN_03192025.pdf
BLAS-12ZLOM501_Affected_CPN_03192025.csv

PCN Status: Final Notification

PCN Type: Manufacturing Change

Microchip Parts Affected: Please open one of the files found in the Affected CPNs section.
Note: For your convenience Microchip includes identical files in two formats (.pdf and .xls)

Description of Change: Qualification of ASEM as a new assembly site for CL8800K63-G-M935, CL8800K63-G, CL8801K63-G and CL8801K63-G-M935 catalog part numbers (CPN) available in 33L VQFN (6x6x1.0 mm) package.

Pre and Post Summary Changes:

	Pre Change	**Post Change**
Assembly Site	Carsem (Suzhou) (CARC)	ASE Group -Malaysia (ASEM)
Wire Material	Au	Au
Die Attach Material	QMI519	QMI519
Molding Compound Material	EME-G770HCD	EME-G770HCD

Lead-Frame	Material	A194	C194
	Paddle Size	173x157 mil	187x159 mil
	Lead-lock Design	See Pre and Post Change Summary for Comparison.	
DAP Surface Prep		Ag	Bare Copper

Note: *C194, A194 or CDA194 Lead frame material are the same, it is just a MCHP internal labelling difference.

Impacts to Datasheet: None

Change Impact: None

Reason for Change: To improve on-time delivery performance by qualifying ASEM as a new assembly site.

Change Implementation Status: In Progress

Estimated First Ship Date: 28 April 2025 (date code: 2518)

Note Below EFSD: Note: Please be advised that after the estimated first ship date customers may receive pre and post change parts.

Timetable Summary:

	May 2024					**>**	**March 2025**					**April 2025**				
Work Week	18	19	20	21	22		09	10	11	12	13	14	15	16	17	18
Initial PCN Issue Date			X													
Qual Report Availability										X						
Final PCN Issue Date										X						
Estimated Implementation Date																X

Method to Identify Change: Traceability Code

Qualification Report: Please open the attachments included with this PCN labeled as PCN_#_Qual_Report.

Revision History:

May 16, 2024: Issued initial notification.
March 19, 2025: Issued final notification. Attached the Qualification Report. Provided Estimated First Ship Date on April 28, 2025.

Note: The change described in this PCN does not alter Microchip's current regulatory compliance regarding the material content of the applicable product.

Attachments:

PCN_BLAS-12ZLOM501-Pre and Post Change Summary.pdf
PCN_BLAS-12ZLOM501-Qual_Report.pdf

Please contact your local **Microchip sales office** with questions or concerns regarding this notification.

Terms and Conditions:

If you wish to receive Microchip PCNs via email please register for our PCN email service at our **PCN home page** select register then fill in the required fields. You will find instructions about registering for Microchips PCN email service in the **PCN FAQ** section.

If you wish to change your PCN profile, including opt out, please go to the **PCN home page** select login and sign into your myMicrochip account. Select a profile option from the left navigation bar and make the applicable selections.

BLAS-12ZLOM501 - CCB 6950 Final Notice: Qualification of ASEM as a new assembly site for CL8800K63-G-M935, CL8800K63-G, CL8801K63-G and CL8801K63-G-M935 catalog part numbers (CPN) available in 33L VQFN (6x6x1.0 mm) package.

Affected Catalog Part Numbers (CPN)

CL8800K63-G-M935

CL8800K63-G

CL8801K63-G

CL8801K63-G-M935

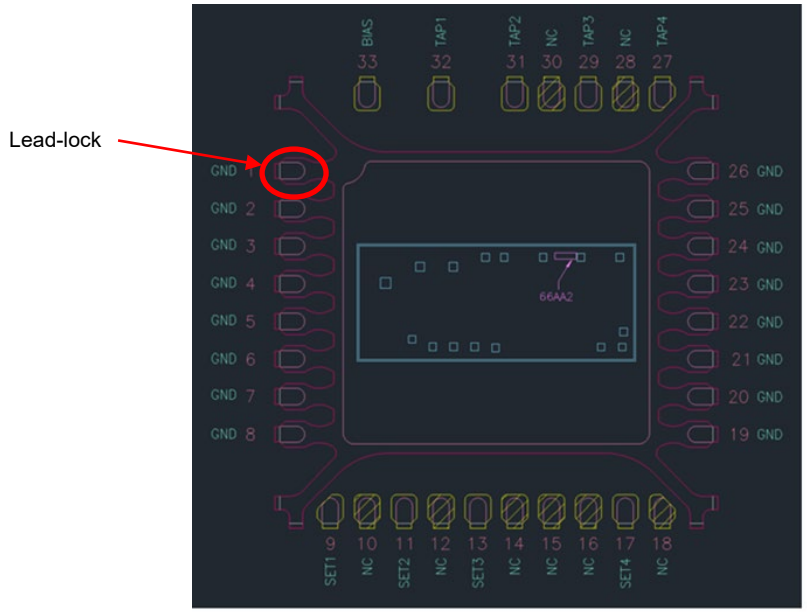
Date: Monday, March 17, 2025

CCB 6950
Pre and Post Change Summary
PCN #: BLAS-12ZLOM501

A Leading Provider of Smart, Connected and Secure Embedded Control Solutions

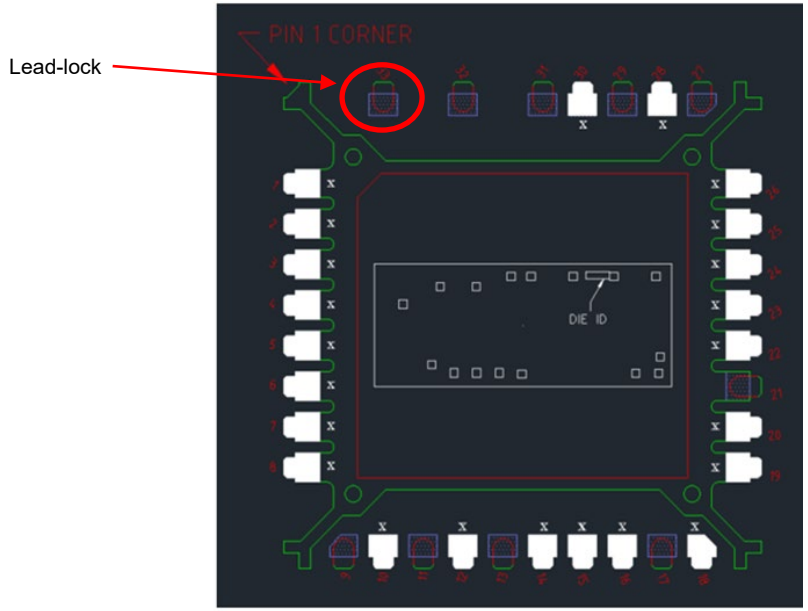
Lead Frame Comparison

CARC



Lead-Frame Material	A194
Lead-lock Design	Half Etched
Lead-frame Paddle Size	173x157 mil

ASEM



Lead-Frame Material	C194
Lead-lock Design	Locking hole & half etch bottom
Lead-frame Paddle Size	187x159 mil

Note 1: Mold compound materials fills the leadlock hole, which provides improved protection against moisture penetration along the edge of leads (pins) of the package.
Note 2: C194, A194 or CDA194 Lead-Frame material are the same, it is just a MCHP internal labelling difference.
Note 3: Not to scale

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QUALIFICATION REPORT SUMMARY

RELIABILITY LABORATORY

PCN #: BLAS-12ZLOM501

Date:
March 11, 2025

Qualification of ASEM as a new assembly site for CL8800K63-G-M935, CL8800K63-G, CL8801K63-G and CL8801K63-G-M935 catalog part numbers (CPN) available in 33L VQFN (6x6x1.0 mm) package.

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PACKAGE QUALIFICATION REPORT

Purpose	Qualification of ASEM as a new assembly site for CL8800K63-G-M935, CL8800K63-G, CL8801K63-G and CL8801K63-G-M935 catalog part numbers (CPN) available in 33L VQFN (6x6x1.0 mm) package.
CN	E000232691
QUAL ID	R2401011 Rev. A
MP CODE	66AA2Y3FXA00
Part No.	CL8801K63-G-M935
Bonding No.	BD-002299 Rev. 01
CCB No.	6950

Package

Type	33L VQFN
Package size	6 x 6 x 1.0mm

Lead Frame

Paddle size	187 x 159 mil
Material	C194 FH
Surface	Bare Copper
Process	Etched
Lead Lock	Locking hole & half etch bottom
Part Number	170033001135UHD

Material

Epoxy	QMI519
Wire	Au wire
Mold Compound	EME-G770HCD
Plating Composition	Matte Sn

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PACKAGE QUALIFICATION REPORT

Manufacturing Information

Assembly Lot No.	Wafer Lot No.	Date Code
ASEM251100058.000	TMPE224275761.500	24247MS
ASEM251100059.000	TMPE224275761.500	24247P4
ASEM251100060.000	TMPE224275761.500	24247PW

Result [X] Pass [ ] Fail [ ] _____

33L VQFN (6x6x1.0mm) assembled by ASEM pass reliability test per QCI-39000. This package was qualified the Moisture/Reflow Sensitivity Classification Level 3 at 260°C reflow temperature per IPC/JEDEC J-STD-020E standard.

PACKAGE QUALIFICATION REPORT

Test Number (Reference)	Test Condition	Standard/ Method	Qty. (Acc.)	Def/SS	Result	Remarks
<u>Precondition Prior Perform Reliability Tests</u> (At MSL Level 3)	**Electrical Test:** +25°C System: TMT_HV_NT	JESD22-A113	693(0)	0/693	Pass	Good Devices
	Bake 150°C, 24 hrs. System: CHINEE	JIP/ IPC/JEDEC J-STD-020E		693		
	30°C/60%RH Moisture Soak 192 hrs. System: TABAI ESPEC Model PR-3SPH			693		
	3x Convection-Reflow 265°C max System: Vitronics Soltec MR1243			693		
	Electrical Test: +25°C System: TMT_HV_NT		693(0)	0/693	Pass	

PACKAGE QUALIFICATION REPORT

Test Number (Reference)	Test Condition	Standard/ Method	Qty. (Acc.)	Def/SS.	Result	Remarks
Temp Cycle	**Stress Condition:** -65°C to +150°C, 500 Cycles System: TABAI ESPEC TSA-70H	JESD22-A104		231		Parts had been pre-conditioned at 260°C
	Electrical Test: +25°C System: TMT_HV_NT		231(0)	0/231	Pass	77 units / lot
	Bond Strength: Wire Pull (>4.00 grams)		15(0)	0/15	Pass	
UNBIASED-HAST	**Stress Condition:** +130°C/85%RH, 96 hrs. System: TMT_HV_NT	JESD22-A118		231		Parts had been pre-conditioned at 260°C
	Electrical Test: +25°C System: SPEA C600 Compact		231(0)	0/231	Pass	77 units / lot
HAST	**Stress Condition:** +130°C/85%RH, 96 hrs. **Bias Volt:** 35 Volts System: HAST 6000X	JESD22-A110		231		Parts had been pre-conditioned at 260°C
	Electrical Test: +25°C System: TMT_HV_NT		231(0)	0/231	Pass	77 units / lot

PACKAGE QUALIFICATION REPORT

Test Number (Reference)	Test Condition	Standard/ Method	Qty. (Acc.)	Def/SS.	Result	Remarks
High Temperature Storage Life	**Stress Condition:** Bake 175°C, 504 hrs. System: TPS Bake Oven **Electrical Test:** +25°C System: TMT_HV_NT	JESD22-A103	 45(0)	0/45 0/45	 Pass	45 units
Solderability Temp 215°C	**Steam Aging:** Temp 93°C,8Hrs System: SAS-3000 **Solder Dipping:** Solder Temp.215°C **Solder material:** SnPb Sn63, Pb37 System: ERSA RA 2200D **Visual Inspection:** External Visual Inspection	J-STD-002	 22(0)	22 22 0/22	 Pass	
Solderability Temp 245°C	**Steam Aging:** Temp 93°C,8Hrs System: SAS-3000 **Solder Dipping:** Solder Temp.245°C **Solder material:** Pb Free Sn 95.5Ag3.9 Cu0.6 System: ERSA RA 2200D **Visual Inspection:** External Visual Inspection	J-STD-002	 22(0)	22 22 0/22	 Pass	
Physical Dimensions	Physical Dimension, 10 units / 1 lot	JESD22-B100/B108	30(0)	0/30	Pass	
Bond Strength Data Assembly	Wire Pull (>4.00 grams) Bond Shear (>14.00 grams)	Mil. Std. 883-2011 CDF-AEC-Q100-001	30(0) Wires 30(0) Bonds	0/30 0/30	Pass Pass	